

RoHS Certificate Of Compliance

Product Number Effective Date FC4-16IP 12/8/2010

This 'Certificate of Compliance' warrants that the product identified above, (and all spares, features and FRUs associated with referenced product) are manufactured in compliance with the Restriction of Hazardous Substances (RoHS), Directive 2002/95/EC. The RoHS Directive restricts the use of certain substances in electronic products; including certain allowable exemptions as noted.

□ Allowable E	-
✓ 6a - I	Lead as an alloying element in steel containing up to 0.35% lead by weight.
☐ 6b - I	Lead as an alloying element in aluminum containing up to 0.4% lead by weight.
	Lead as an alloying element in copper containing up to 4% lead by weight.
▼ 7a - I 85%	Lead in high melting temperature type solders (i.e. lead based solder alloys containing by weight or more lead).
🔽 equij	Lead in solders for servers, storage and storage array systems, network infrastrucutre pment for switching, signalling, transmission as well as network management for ommunications. This applies only to Ball Grid Array (BGA) components.
🔽 than	Electrical and electronic components containing lead in a glass or ceramic other dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or mic matrix compound
	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V or higher
7cIII or 25	- Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC 0 V DC.
▼ 11b -	Lead used in other than C-press compliant pin connector systems
☐ 13 - I	Lead in optical & filter glass.
✓ ^{15 - I}	Lead in solders to complete a viable electrical connection between semiconductor die and er within integrated circuit flip chip packages
Comments (if a	oplicable):
· -	
Signature (hand	dwritten or electronic signature):

Printed Name: Carrie Rich

Title: Environmental Compliance Manager

Date: 12/8/2010

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